

## SEMICONDUCTOR CHIP

## BACKGROUND OF THE INVENTION

## 5           1.     Field of the Invention

          The present invention relates to a semiconductor chip having a monitor circuit for finding a critical path delay characteristic of a target circuit subjected by power supply voltage control, more particularly relates to technology for adaptively  
10   controlling a power supply voltage supplied to a target circuit LSI so as to reduce the power consumption.

## 2.     Description of the Related Art

          In recent years, in semiconductor circuits,  
15   it has been attempted to lower the power supply voltage so as to lower the power consumption. The reason is that an AC component of the consumed power of a semiconductor integrated circuit (LSI) is proportional to the square of the power supply voltage ( $V^2$ ), so lowering the power  
20   supply voltage would be the most effective for lowering the power consumption of an LSI.

          From such a viewpoint, in recent years, the method of dynamically controlling the power supply voltage with respect to the operating frequency of the  
25   LSI, process variations, and temperature changes so as to

adaptively supply the minimum voltage enabling LSI operation has been reported.

As an example of realization of such adaptive power supply voltage control, it is known to mount a replica circuit for imitating a delay corresponding to the critical path of a target circuit on the same chip as the target circuit subjected by the power supply voltage control (see for example Japanese Unexamined Patent Publication (Kokai) No. 2000-216338, Japanese Unexamined Patent Publication (Kokai) No. 2000-295084, and Japanese Unexamined Patent Publication (Kokai) No. 2002-100967).

In those methods, the period of the clock signal supplied to the target circuit and the delay value of the replica circuit are compared and the power supply voltage is controlled so that the delay value of the replica circuit fits in an operation clock cycle.

Summarizing the disadvantages to be solved by the invention, usually, produced LSIs feature various variations in characteristics. For example, individual LSIs will differ in the relationship between the power supply voltage  $V_{dd}$  supplied to the LSIs and the maximum clock frequency  $f_{clk-max}$  at which the operation of the LSIs is guaranteed.

FIG. 6 is a graph of examples of the relationship between the power supply voltage  $V_{dd}$  and the

maximum clock frequency  $f_{clk-max}$ . In FIG. 6, an abscissa indicates the power supply voltage  $V_{dd}$ , and an ordinate indicates the maximum clock frequency  $f_{clk-max}$ .

A curve C1 shows the characteristic of a high speed LSI having the highest operating speed within the range of variation of characteristics. A curve C3 shows the characteristic of a low speed LSI having the lowest operation speed in this range of variation. A curve C2 shows the representative characteristic in this range of variation.

As shown in FIG. 6, in general, the maximum clock frequency  $f_{clk}$  of a circuit tends to rise as the power supply voltage  $V_{dd}$  becomes higher. For this reason, when the same power supply voltage is given, an LSI having the characteristic of the curve C1 can be operated at a high speed at a clock frequency higher than LSIs having the characteristics of the curves C2 and C3.

When viewing this relationship for the same clock frequency, an LSI able to perform high speed operation becomes able to perform the operation at a power supply voltage lower than an LSI of a low speed. For example, in FIG. 6, in the case of a clock frequency  $f_1$ , an LSI having the characteristic of the curve C3 requires a power supply voltage larger than the voltage  $V_3$  at the minimum, but LSIs having the characteristics of

the curves C1 and C2 can operate at power supply voltages of as low as the voltages V1 and V2 smaller than that.

In general, since LSIs have such variations in characteristic, usually, in any sample, the operation  
5 of the LSI is guaranteed by supplying a power supply voltage the same as the voltage V3 or higher in a fixed manner.

As opposed to this, according to the above mentioned technique of controlling the power supply  
10 voltage in accordance with the delay characteristic of the target circuit as determined by the replica circuit, the power supply voltage of an LSI having a high speed characteristic can be suppressed lower than the power supply voltage of an LSI having a low speed  
15 characteristic. Therefore, the power consumption can be reduced further in comparison with the method of supplying a fixed power supply voltage.

Along with the reduction in the design rule and the increase in wafer size in recent years, however,  
20 not only the variation between different semiconductor wafers and the variation in the same wafer, but also local variation of characteristics in the same chip have become conspicuous. Namely, even in the same chip, non-ignorable deviations occur in the characteristics of  
25 transistors formed at different positions due to minute

fluctuations in the production conditions.

Such variation of characteristics in the same chip occurs also between the replica circuit and the target circuit. Therefore, when controlling the power supply voltage by using a replica circuit, it is necessary to consider the amount of such variation in characteristics.

FIG. 7 is a graph illustrating a range of operation power supply voltage taking into account a local difference of characteristics between the target circuit and the replica circuit.

The range of power supply voltage in which normal operation is guaranteed in a target circuit covered by power supply voltage control becomes a range from the low limit voltage  $V_{ll}$  to the high limit voltage  $V_{lh}$  if considering only local variation of characteristics of the target circuit itself. Contrary to this, the range of power supply voltage when considering the local variation of characteristics of the replica circuit as well becomes a range from the low limit voltage  $V_{rl}$  to the high limit voltage  $V_{rh}$ , that is, is shifted to the high voltage side in comparison with the range from the low limit voltage  $V_{ll}$  to the high limit voltage  $V_{lh}$ . To prevent malfunctions in the target circuit due to shortage of the supplied voltage, it is

necessary to set the low limit voltage  $V_{rl}$  to a voltage the same as the high limit voltage  $V_{lh}$  or higher.

FIG. 8 is a graph illustrating the range of operating power supply voltage taking into consideration the local difference of characteristics between the target circuit covered by the power supply voltage control and the replica circuit for LSIs having characteristics of the curves C1 to C3 shown in FIG. 6.

The voltage  $V_3$  indicates a power supply voltage required for normally operation of the target circuit of the LSI having the lowest speed characteristic at the clock frequency  $f_1$ . When using this circuit while fixing the clock signal at the frequency  $f_1$ , by supplying even the power supply voltage of this voltage  $v_3$ , normal operation of the target circuit is guaranteed. In the example of FIG. 8, in the LSIs from the middle speed to the high speed having the characteristics of the curves C1 and C2, even if taking into consideration the local difference of characteristics, the maximum value  $V_{rh}$  of the power supply voltage determined from the delay characteristic of the replica circuit will never exceed this voltage  $V_3$ .

When the LSI has a relatively low speed characteristic, however, the maximum value  $V_{rh}$  of the power supply voltage determined from the delay

characteristic of the replica circuit may become larger than the voltage V3. In such a case, in comparison with the method of supplying a fixed power supply voltage of the voltage V3, the disadvantage arises that the power  
5 consumption rather increases.

For example, in the case of the lowest speed LSI having the characteristic of the curve C3, an excess voltage ( $V_{rh}-V_{rl}$ ) corresponding to the variation of characteristics of the replica circuit is added to the  
10 voltage V3, therefore a wasteful voltage loss due to this excess voltage is induced.

#### SUMMARY OF THE INVENTION

An object of the present invention is to provide a semiconductor chip able to reduce wasteful power loss due  
15 to the margin of the power supply voltage set for taking into account the variation of characteristics.

According to the present invention, there is provided a semiconductor chip including: a delay monitoring means for finding a critical path delay  
20 characteristic of a target circuit subjected by power supply voltage control; a voltage setting signal generating means for generating a voltage setting signal for setting a power supply voltage to be supplied to the target circuit based on the result of monitoring of delay  
25 by the delay monitoring means; and a voltage setting

restricting means for restricting the maximum value of the power supply voltage set in the voltage setting signal to a predetermined value.

According to the semiconductor chip of the present invention, the voltage setting signal generating means generates the voltage setting signal for setting the power supply voltage to be supplied to the target circuit based on the result of monitoring of delay by the delay monitoring means. The maximum value of the power supply voltage set in this voltage setting signal is restricted to a predetermined value by the voltage setting restricting means, for example, to the maximum value of the power supply voltage determined based on variations in production of the semiconductor chip.

Accordingly, even if the value of the power supply voltage set based on the result of monitoring of delay by the delay monitoring means exceeds this predetermined value, the voltage setting restricting means restricts the voltage setting of the voltage setting signal to this predetermined value.

The voltage setting restricting means may determine the maximum value of the power supply voltage to be restricted in accordance with a signal indicating an operation state of the target circuit, for example, a signal indicating an operation clock frequency of the



target circuit.

In this case, the voltage setting restricting means may have a first storing means for storing a maximum voltage setting signal for setting the maximum value of the power supply voltage to be restricted, and a  
5 comparing means for comparing the maximum value of the power supply voltage set by the maximum voltage setting signal stored in the first storing means with the value of the power supply voltage set by the voltage setting  
10 signal and outputting the signal having a lower voltage setting and further may have a second storing means storing a plurality of maximum voltage setting signals and a maximum voltage signal transferring means for reading out a maximum voltage setting signal selected in  
15 accordance with the signal indicating the operation state of the target circuit from the second storing means and transferring the same to the first storing means.

According to the above circuit configuration, the maximum setting signal corresponding to the signal  
20 indicating the operation state of the target circuit is selected by the maximum voltage signal transferring means from among the plurality of maximum voltage setting signals stored in the second storing means, read out, and transferred to the first storing means. The comparing  
25 means compares the maximum value of the power supply

voltage set by the maximum voltage setting signal stored in the first storing means with the value of the power supply voltage set by the voltage setting signal and outputs the signal having a lower voltage setting.

5           The voltage setting restricting means may include a plurality of first storing means for storing maximum voltage setting signals for setting the maximum value of the power supply voltage to be restricted; a selecting means for selecting a maximum voltage setting signal  
10           corresponding to a signal indicating the operation state of the target circuit from among the maximum voltage setting signals stored in the plurality of first storing means; and a comparing means for comparing the maximum value of the power supply voltage set by the maximum  
15           voltage setting signal selected by the selecting means with the value of the power supply voltage set by the voltage setting signal and outputting the signal having a lower voltage setting.

          According to the above circuit configuration, the  
20           selecting means selects the maximum voltage setting signal corresponding to a signal indicating the operation state of the target circuit from among the maximum voltage setting signals stored in the plurality of first storing means. The comparing means compares the maximum  
25           value of the power supply voltage set by the maximum

voltage setting signal selected by the selecting means with the value of the power supply voltage set by the voltage setting signal and outputs the signal having a lower voltage setting.

5           The first storing means may be a storing means able to electrically erase and rewrite the stored signals or may be a storing means including one or more fuse circuits and storing signals according to a conductive state or a nonconductive state of the fuse in the fuse  
10   circuits.

#### BRIEF DESCRIPTION OF THE DRAWINGS

These and other objects and features of the present invention will become clearer from the following description of the preferred embodiments with reference  
15   to the accompanying drawings, in which:

FIG. 1 is a block diagram of an example of the circuit configuration of a semiconductor chip according to a first embodiment of the present invention;

FIG. 2 is a block diagram of an example of the  
20   configuration of a power supply voltage controller included in a semiconductor chip according to the first embodiment of the present invention;

FIG. 3 is a diagram of a pulse generator, a replica circuit, and a power supply voltage controller included  
25   in a semiconductor chip according to a second embodiment

of the present invention;

FIG. 4 is a block diagram of an example of the configuration of the power supply voltage controller included in a semiconductor chip according to the second  
5 embodiment of the present invention;

FIG. 5 is a block diagram of an example of the configuration of the power supply voltage controller included in a semiconductor chip according to a third embodiment of the present invention;

10 FIG. 6 is graph illustrating examples of the relationship between the power supply voltage and the maximum clock frequency in an embodiment of the present invention;

FIG. 7 is a graph illustrating a range of operation  
15 power supply voltage in a case taking into account a local difference of characteristics between a target circuit subjected by power supply voltage control and a replica circuit in an embodiment of the present invention; and

20 FIG. 8 is a graph illustrating a range of operation power supply voltage taking into account a local difference of characteristics between a target circuit subjected by power supply voltage control and a replica circuit in an embodiment of the present invention for  
25 LSIs having characteristics of curves shown in FIG. 6.

## DESCRIPTION OF THE PREFERRED EMBODIMENTS

Below, preferred embodiments will be described with reference to the accompanying drawings.

First Embodiment

5        FIG. 1 is a block diagram of an example of the circuit configuration of a semiconductor chip according to a first embodiment of the present invention.

         A semiconductor chip 11 has a target circuit (TGT) 11 subjected by power supply voltage control, a pulse  
10 generator (PG) 12, a replica circuit (RPLC) 13 having an operation time substantially the same as the target circuit (TGT) 11, and a power supply voltage controller (PW-CTL) 14.

         The semiconductor chip 11 operates by receiving  
15 power supply voltage Vdd of an external power supply (EXT-PW) 2 controlled in voltage value in accordance with a voltage setting signal S14.

         Note that the target circuit 11 is an embodiment of the target circuit subjected by power supply voltage  
20 control of the present invention.

         The target circuit 11 includes main circuits of the semiconductor chip 1. For example, it includes a digital signal processor (DSP) operating in synchronization with a clock signal CLK output from the pulse generator 12, a  
25 CPU (central processor unit), and other various circuits.

These circuits operate by receiving the power supply voltage Vdd supplied from the external power supply 2.

The pulse generator 12 generates the clock signals CLK supplied to the target circuit 11 and the replica  
5 circuit 13.

The replica circuit 13 is a circuit for finding the critical path delay characteristic of the target circuit 11 subjected by power supply voltage control and is an embodiment of the delay monitoring means of the present  
10 invention.

The replica circuit 13 has a plurality of delay elements operating when supplied with the power supply voltage Vdd common to that for, for example, the target circuit 11. These delay elements imitate the delay  
15 components which become factors of signal propagation delay inside the target circuit 11. The clock signal CLK supplied to the replica circuit 13 is given a delay imitated in this way and output as a delay signal S13.

The power supply voltage controller 14 generates  
20 the voltage setting signal S14 for setting the power supply voltage Vdd to be supplied to the target circuit 11 based on the delay of the delay signal S13 output from the replica circuit 13 with respect to the clock signal CLK. Note that the maximum value of the power supply  
25 voltage Vdd set by the voltage setting signal S14 is

restricted to a predetermined value. For example, it is restricted to the maximum value  $V_{max}$  of the power supply voltage determined based on the result of inspection of variations in production of the semiconductor chip 11.

- 5 For this reason, the power supply voltage  $V_{dd}$  supplied from the external power supply (EXT-PW) 2 is restricted to the maximum value  $V_{max}$ .

FIG. 2 is a block diagram of an example of the configuration of the power supply voltage controller 14 shown in FIG. 1.

The power supply voltage controller 14 has a voltage setting signal generator (V-SET) 141, a comparator (COMP) 142, and a register (REG) 143.

15 The voltage setting signal generator 141 is an embodiment of the voltage setting signal generating means of the present invention. The comparator 142 is an embodiment of the comparing means of the present invention. The register 143 is an embodiment of the first storing means of the present invention. The unit  
20 including the comparator 142 and the register 143 is an embodiment of the voltage setting restricting means of the present invention.

The voltage setting signal generator 141 detects a delay time of the delay signal  $S_{13}$  output from the  
25 replica circuit 13 with respect to the clock signal CLK

and generates a voltage setting signal S141 for setting the power supply voltage Vdd to be supplied to the target circuit 11 based on this detection result.

Looking at the voltage setting signal S141, for example, phases of the clock signal CLK and the delay signal S13 of the replica circuit 13 are compared. When the delay signal S13 is delayed by one cycle or more from the clock signal CLK, a voltage setting signal S141 set so as to raise the power supply voltage Vdd is generated. When the delay signal S13 is advanced by one cycle or more, a voltage setting signal S141 set so as to make the power supply voltage Vdd lower is generated.

The register 143 stores the maximum voltage setting signal S143 for setting the maximum value Vmax of the power supply voltage to be restricted.

As the register 143, use can be made of for example a storage device such as a RAM or flash ROM able to electrically erase stored signals and rewrite the data. By using such an electrically rewritable storage device, after the production and evaluation of the semiconductor chip, a suitable maximum value Vmax for the individual semiconductor chip can be set. Further, even after a semiconductor chip is shipped from the factory producing the semiconductor chips, the set maximum value Vmax can be easily changed.



The register 143 may also be a storage device for storing a signal according to whether a fuse in one or more fuse circuits is in the conductive state or the nonconductive (disconnected) state. Even when using such  
5 a storage device, a suitable maximum value  $V_{max}$  for an individual semiconductor chip can be set. The value is physically written by the disconnection of fuses, therefore a once written value cannot be changed, but the circuit size and the power consumption can be made  
10 smaller in comparison with an electrically rewritable storage device.

The comparator 142 compares the maximum value  $V_{max}$  of the power supply voltage set by the maximum voltage setting signal  $S_{143}$  stored in the register 143 with the  
15 value of the power supply voltage set by the voltage setting signal  $S_{141}$  and outputs the signal having a lower voltage setting as the voltage setting signal  $S_{141}$ . Accordingly, where the value of the power supply voltage set by the voltage setting signal  $S_{141}$  exceeds the  
20 maximum value  $V_{max}$ , the voltage setting of the voltage setting signal  $S_{14}$  is restricted to the maximum value  $V_{max}$ .

Next, an explanation will be given of the control operation of the power supply voltage  $V_{dd}$  in a  
25 semiconductor chip 1 having the above configuration.

The clock signal CLK generated at the pulse generator 12 is given a delay imitating the signal propagation delay characteristic of the target circuit 11 by the replica circuit 13 and output as the delay signal S13.

The voltage setting signal generator 141 detects the delay time of this delay signal S13 with respect to the clock signal CLK and generates a voltage setting signal S141 for setting the power supply voltage Vdd to be supplied to the target circuit 11 based on this detection result.

The generated voltage setting signal S141 is compared with the maximum voltage setting signal S143 stored in the register 143 at the comparator 142, and the signal having a lower voltage setting is output as the voltage setting signal S14 to the external power supply 2.

At the external power supply 2, the power supply voltage Vdd to be supplied to the semiconductor chip 1 is controlled so as to become equal to the voltage set by this voltage setting signal S14.

According to the semiconductor chip 1 having the configuration shown in FIG. 1 and FIG. 2, the magnitude of the power supply voltage Vdd is set in accordance with the delay characteristic of the target circuit 11 determined based on the delay signal S13 of the replica

circuit 13. When the voltage set in this way reaches the maximum value  $V_{max}$ , the voltage setting with respect to the external power supply 2 is restricted so as not to exceed this maximum value  $V_{max}$ .

5           Accordingly, in a semiconductor chip 1 having a low speed characteristic as indicated by the curve C3 of FIG. 6, even in a case where the voltage setting of the voltage setting signal S141 generated based on the delay signal S13 of the replica circuit 13 exceeds the maximum  
10 value  $V_{max}$  due to the margin set considering the variation of characteristics between the target circuit and the replica circuit 13, the voltage set with respect to the external power supply 2 can be restricted to this maximum value  $V_{max}$  or less. As a result, the excessive  
15 supply of the power supply voltage exceeding the maximum value  $V_{max}$  can be prevented, and wasteful power loss can be reduced.

#### Second Embodiment

FIG. 3 is a block diagram of a pulse generator 12,  
20 a replica circuit 13, and a power supply voltage controller 14A included in a semiconductor chip 1A according to a second embodiment of the present invention.

The difference of the second embodiment from the first embodiment resides in that the power supply voltage  
25 controller 14 shown in FIG. 1 is replaced by the power

supply voltage controller 14A explained below.

The power supply voltage controller 14A generates a voltage setting signal S14 for setting the power supply voltage Vdd to be supplied to the target circuit 11 based on the delay of the delay signal S13 output from the replica circuit 13 with respect to the clock signal CLK. Note that the maximum value of the power supply voltage Vdd set by the voltage setting signal 14 is restricted to the maximum value Vmax of the power supply voltage determined based on for example the result of inspection of variations in production of the semiconductor chip 11.

The power supply voltage controller 14A determines the maximum value Vmax of the power supply voltage to be restricted in accordance with a signal indicating the operation state of the target circuit 11, for example, a signal Smod indicating the frequency of the clock signal CLK supplied to the target circuit 11.

FIG. 4 is a block diagram of an example of the configuration of the power supply voltage controller 14A shown in FIG. 3.

The power supply voltage controller 14A shown in FIG. 4 has a voltage setting signal generator 141, a comparator 142, registers 143-0, ..., 143-3, and a selector 144. Note that the same notations in FIG. 4 and FIG. 2 indicate the same components.

The registers 143-0, ..., 143-3 are an embodiment of the plurality of first storing means of the present invention. The selector 144 is an embodiment of the selecting means of the present invention. The unit  
5 including the comparator 142, the registers 143-0, ..., 143-3, and the selector 144 is an embodiment of the voltage setting restricting means of the present invention.

The registers 143-0, ..., 143-3 store the maximum  
10 voltage setting signals S143-0 to S143-3 for setting a plurality of power supply voltage maximum values Vmax0 to Vmax3 determined in accordance with the frequency of the clock signal CLK to be supplied to the target circuit 11.

For the registers 143-0, ..., 143-3, in the same way  
15 as the register 143, electrically erasable and rewritable storage devices, storage devices including fuse circuits, etc. can be applied.

The selector 144 selects a signal corresponding to the signal Smod indicating the frequency of the clock  
20 signal CLK from among the maximum voltage setting signals S143-0 to S143-3 stored in the registers 143-0, ..., 143-3 and outputs the same as the maximum voltage setting signal S143.

According to the semiconductor chip 1A having the  
25 above configuration, in the same way as the above

semiconductor chip 1, the voltage setting signal S141 for setting the power supply voltage Vdd to be supplied to the target circuit 11 is generated based on the delay time of the delay signal S13 of the replica circuit 13  
5 with respect to the clock signal CLK.

Further, the selector 144 selects a signal corresponding to the signal Smod indicating the frequency of the clock signal CLK from among the plurality of maximum voltage setting signals S143-0 to S143-3 and  
10 outputs the same as the maximum voltage setting signal S143.

The comparator 142 compares the maximum voltage setting signal S143 selected at the selector 144 with the generated voltage setting signal S141 and outputs the  
15 signal having a lower voltage setting as the voltage setting signal S14 to the external power supply 2.

The external power supply 2 controls the power supply voltage Vdd to be supplied to the semiconductor chip 1 so as to become equal to the voltage set by this  
20 voltage setting signal S14.

In this way, according to the semiconductor chip 1A, the voltage setting with respect to the external power supply 2 is restricted so as not to exceed the maximum value Vmax. Therefore, in the same way as the  
25 semiconductor chip 1, power loss can be reduced.

This maximum value  $V_{\max}$  is determined in accordance with a signal  $S_{\text{mod}}$  indicating the operation state of the target circuit 11 such as for example a signal indicating the clock frequency to be supplied to the target circuit 11. For this reason, even when the operation state of the target circuit 11 changes, the maximum value  $V_{\max}$  of a suitable power supply voltage is set in accordance with this change. Accordingly, wasteful power loss due to the supply of excess power supply voltage can be effectively suppressed.

When the operation clock frequency is the frequency  $f_1$  in FIG. 6, by setting the maximum value  $V_{\max}$  of the voltage setting with respect to the external power supply 2 to the voltage  $V_3$ , the supply of excess power supply voltage can be effectively prevented. When the operation clock frequency is changed to the frequency  $f_2$  lower than the frequency  $f_1$ , however, the minimum operation power supply voltage considering variations in production becomes lower than the voltage  $V_3$ . In this state, if the maximum value  $V_{\max}$  (voltage  $V_3$ ) of the frequency  $f_1$  is used as it is, there is a possibility that an excess power supply voltage will be supplied regardless of the fact that operation is possible even at a lower power supply voltage. According to the above semiconductor chip 1A, the suitable maximum value  $V_{\max}$  is selected in

accordance with the signal Smod indicating the operation clock frequency. Therefore, the excess supply of the power supply voltage is prevented, and wasteful power loss can be reduced.

5           Along with the spread of mobile electronic devices, reduction of power consumption has become a major issue. The technique of lowering of power consumption by dynamically changing the clock frequency in accordance with the operating state of the device is frequently  
10 employed. If the above semiconductor chip 1A is applied to such an electronic device, since the suitable maximum value of the power supply voltage is set in accordance with the operation clock frequency, wasteful power loss can be further reduced:

15           Third Embodiment

FIG. 5 is a block diagram of an example of the configuration of a power supply voltage controller 14B included in a semiconductor chip 1B according to a third embodiment.

20           The difference of the third embodiment from the first embodiment resides in that the power supply voltage controller 14 shown in FIG. 1 is replaced by the power supply voltage controller 14B shown in FIG. 5.

          The power supply voltage controller 14B shown in  
25 FIG. 5 has the same configuration as that of the power



supply voltage controller 14 shown in FIG. 2 and, at the same time, has a memory 145 and a maximum voltage signal loader 146.

The memory 145 is an embodiment of the second  
5 storing means of the present invention.

The maximum voltage signal loader 146 is an embodiment of the maximum voltage signal transferring means of the present invention.

The memory 145 stores a plurality of maximum  
10 voltage setting signals for setting a plurality of power supply voltage maximum values determined in accordance with the operation state of the target circuit 11, for example, the frequency of the clock signal CLK.

As the memory 145, use can be made of various  
15 storage devices such as a SRAM and DRAM. For example, it is also possible to use a general purpose memory accessed also from other circuits in the target circuit 11.

The maximum voltage signal loader 146 reads out the maximum voltage setting signal selected in accordance  
20 with a signal indicating the operation state of the target circuit 11, for example, the signal Smod indicating the frequency of the clock signal CLK, from the memory 145 and transfers (loads) the same to the register 143.

25 According to the semiconductor chip 1B having the

above configuration, in the same way as the semiconductor chip 1, the voltage setting signal S141 for setting the power supply voltage Vdd to be supplied to the target circuit 11 is generated based on the delay time of the delay signal S13 of the replica circuit 13 with respect to the clock signal CLK.

Further, the maximum voltage signal loader 146 reads out the signal selected in accordance with the signal Smod indicating the frequency of the clock signal CLK from among the plurality of maximum voltage setting signals stored in the memory 145 and loads it in the register 143.

The comparator 142 compares the maximum voltage setting signal S143 loaded in the register 143 and the generated voltage setting signal S141 and outputs the signal having a lower voltage setting as the voltage setting signal S14 to the external power supply 2.

The external power supply 2 controls the power supply voltage Vdd to be supplied to the semiconductor chip 1 so as to become equal to the voltage set by this voltage setting signal S14.

In this way, according to the above semiconductor chip 1B, the voltage setting with respect to the external power supply 2 is restricted so as not to exceed the maximum value Vmax. Therefore the power loss can be

suppressed in the same way as the semiconductor chip 1.

This maximum value  $V_{max}$  is determined in accordance with a signal  $S_{mod}$  indicating the operation state of the target circuit 11 such as for example a signal indicating the clock frequency to be supplied to the target circuit 11. Therefore, in the same way as the semiconductor chip 1A, wasteful power loss due to the excess supply of the power supply voltage can be reduced.

Further, according to the semiconductor chip 1B, a configuration loading the maximum voltage setting signal to one register from the general purpose memory 145 is provided. Therefore, in comparison with a configuration providing a plurality of dedicated registers for storing the maximum voltage setting signal as in the semiconductor chip 1A, the circuit size and the power consumption can be made smaller.

Further, with the configuration of the semiconductor chip 1A providing the dedicated registers, an increase of the number of the power supply voltage maximum values to be set cannot be handled without changing the circuit, but according to the semiconductor chip 1B, it is possible to increase the storage region of the maximum voltage setting signals secured in the memory 145 by a change of the software, therefore such a change can be flexibly dealt with.

The present invention is not limited to the above embodiments.

For example, the number of the registers was four in the voltage control circuit 14A shown in FIG. 4, but  
5 the present invention is not limited to this. Any number of registers can be provided.

Further, in the semiconductor chip 1 shown in FIG. 1, the power supply was provided outside of the semiconductor chip, but the present invention is not  
10 limited to this. The present invention can also be applied to a case where part or all of the power supply is included inside the semiconductor chip.

Summarizing the effects and features of the invention, according to the present invention, wasteful  
15 power loss occurring due to the margin of the power supply voltage set considering variations in characteristics can be reduced.

Further, according to the present invention, even when the operation state of the target circuit subjected  
20 by power supply voltage control changes, the maximum value of the suitable power supply voltage corresponding to this is set, and wasteful power loss can be reduced.